imall

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

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Power MOSFET

-20 V, -1.37 A, Single P-Channel, SC-70

Features

- Leading -20 V Trench for Low R_{DS(on)}
- -2.5 V Rated for Low Voltage Gate Drive
- SC-70 Surface Mount for Small Footprint (2x2 mm)
- Pb-Free Package is Available

Applications

- High Side Load Switch
- Charging Circuit
- Single Cell Battery Applications such as: Cell Phones, Digital Cameras, PDAs

MAXIMUM RATINGS ($T_J = 25^{\circ}C$ unless otherwise stated)

Parame	Symbol	Value	Units			
Drain-to-Source Voltage	V _{DSS}	-20	V			
Gate-to-Source Voltage	V _{GS}	±8	V			
Continuous Drain	I _D	-1.37	А			
Current (Note 1)	State	$T_A = 70^{\circ}C$		-0.62		
Power Dissipation (Note 1)	Steady State	$T_A = 25^{\circ}C$	PD	0.329	W	
Pulsed Drain Current	I _{DM}	-4.0	А			
Operating Junction and S	T _J , T _{STG}	–55 to 150	°C			
Source Current (Body Die	I _S	-0.5	А			
Lead Temperature for Soldering Purposes (1/8" from case for 10 s)			ΤL	260	°C	

THERMAL RESISTANCE RATINGS

Parameter	Symbol	Max	Units
Junction-to-Ambient-Steady State (Note 1)	$R_{\theta JA}$	380	°C/W

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. Surface-mounted on FR4 board using 1 in sq pad size

(Cu area = 1.127 in sq [1 oz] including traces).

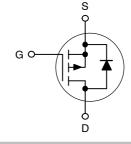


ON Semiconductor®

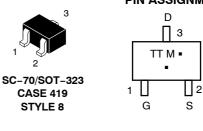
http://onsemi.com

V _{(BR)DSS}	R _{DS(on)} Typ	I _D Max
	83 mΩ @ –4.5 V	
–20 V	88 mΩ @ –3.6 V	–1.37 A
	104 mΩ @ –2.5 V	





MARKING DIAGRAM & PIN ASSIGNMENT



TT

Μ

= Device Code = Date Code*

= Pb-Free Package

(Note: Microdot may be in either location)

*Date Code orientation may vary depending upon manufacturing location.

ORDERING INFORMATION

Device	Package	Shipping [†]
NTS4101PT1	SOT-323	3000/Tape & Reel
NTS4101PT1G	SOT-323 (Pb-Free)	3000/Tape & Reel

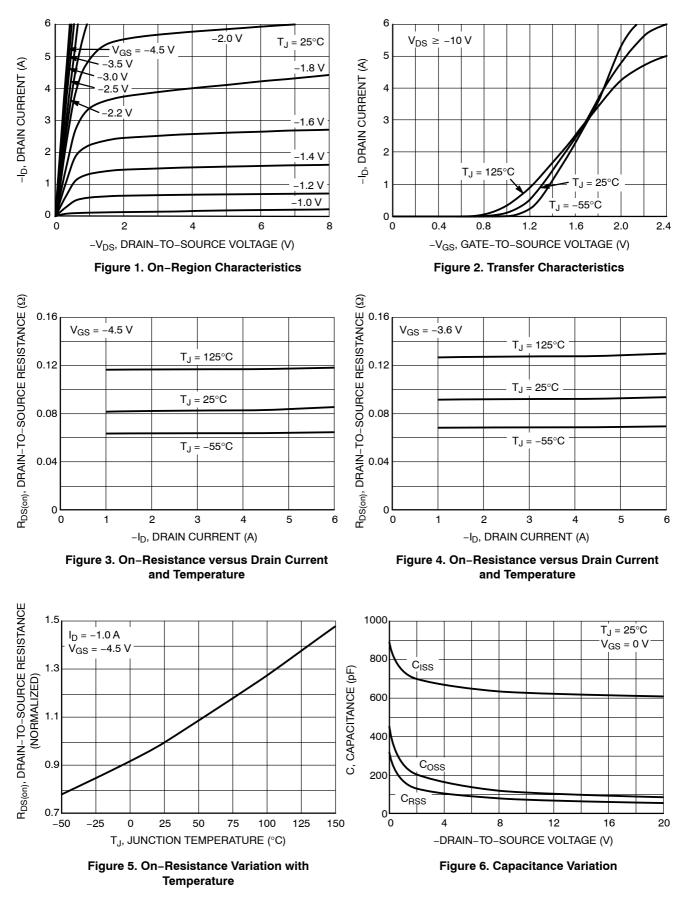
+ For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

ELECTRICAL CHARACTERISTICS (T_J=25°C unless otherwise stated)

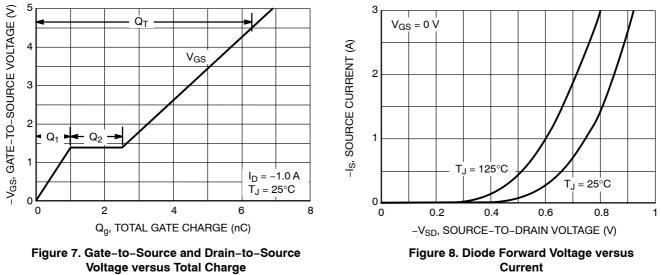
Parameter	Symbol	Test Condition		Min	Тур	Max	Unit	
OFF CHARACTERISTICS	•							
Drain-to-Source Breakdown Voltage	V _{(BR)DSS}	V_{GS} = 0 V, I _D = -250 μ A		-20	-24.5		V	
Drain-to-Source Breakdown Voltage Temperature Coefficient	V _{(BR)DSS} /T _J				-13.7		mV/°C	
Zero Gate Voltage Drain Current	I _{DSS}	V _{GS} = 0 V,	T _J = 25°C			-1.0	μΑ	
		V _{DS} = -16 V	T _J = 70°C			-5.0		
Gate-to-Source Leakage Current	I _{GSS}	V _{DS} = 0 V, V _C	_{as} = ±8 V			±100	nA	
ON CHARACTERISTICS (Note 2)								
Gate Threshold Voltage	V _{GS(TH)}	$V_{GS} = V_{DS}, I_D$	= –250 μA	-0.45	-0.64	-1.5	V	
Negative Threshold Temperature Coefficient	V _{GS(TH)} /T _J				2.7		mV/°C	
Drain-to-Source On Resistance	R _{DS(on)}	V _{GS} = -4.5 V, I	_D = -1.0 A		83	120	mΩ	
		V _{GS} = -3.6 V, I	_D = -0.7 A		88	130		
	V _{GS} = -2.		_D = -0.3 A		104	160	-	
Forward Transconductance	G _{FS}	V_{DS} = -5.0 V, I _D = -1.3 A			5.2		S	
CHARGES AND CAPACITANCES	-				-		•	
Input Capacitance	C _{ISS}	$V_{GS} = 0 V$, f = 1.0 MHz, $V_{DS} = -20 V$			603	840	pF	
Output Capacitance	C _{OSS}				90	125		
Reverse Transfer Capacitance	C _{RSS}				62	85		
Total Gate Charge	Q _{G(TOT)}	V _{GS} = -4.5 V, V _{DS} = -4.5 V,			6.4	9.0	nC	
Threshold Gate Charge	Q _{G(TH)}	I _D = -1.	0 A -		0.7		1	
Gate-to-Source Charge	Q _{GS}				1.0		1	
Gate-to-Drain Charge	Q _{GD}				1.5			
SWITCHING CHARACTERISTICS (No	ote 3)							
Turn-On Delay Time	t _{d(ON)}	V _{GS} = -4.5 V, V _E I _D = -1.0 A, R	$D_{D} = -4.0 \text{ V},$		6.2	12	ns	
Rise Time	t _r	I _D = –1.0 A, R	$_{\rm G}$ = 6.2 Ω		14.9	25	1	
Turn-Off Delay Time	t _{d(OFF)}				26	40		
Fall Time	t _f				18	30		
DRAIN-SOURCE DIODE CHARACTE	RISTICS							
Forward Diode Voltage	V _{SD}	V _{GS} = 0 V,	$T_J = 25^{\circ}C$		-0.61	-1.2	V	
		I _S = -0.3 A	T _J = 125°C		-0.5			
Reverse Recovery Time	t _{RR}	V_{GS} = 0 V, dI_{SD}/dt = 100 A/µs, I_S = -1.0 A			10.9	20	ns	
Charge Time	T _a				7.1			
Discharge Time	T _b				3.8			
Reverse Recovery Charge	Q _{RR}				4.25		nC	

Pulse Test: pulse width ≤ 300 μs, duty cycle ≤ 2%.
Switching characteristics are independent of operating junction temperatures.

TYPICAL CHARACTERISTICS



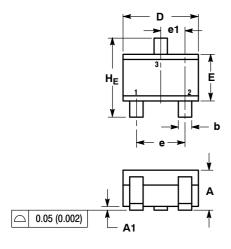
TYPICAL CHARACTERISTICS



Voltage versus Total Charge

PACKAGE DIMENSIONS

SC-70 (SOT-323) CASE 419-04 ISSUE N

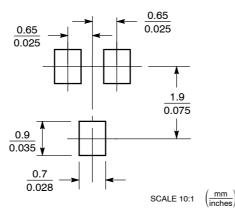


NOTES: 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: INCH.

	MILLIMETERS			INCHES			
DIM	MIN	NOM	MAX	MIN	NOM	MAX	
Α	0.80	0.90	1.00	0.032	0.035	0.040	
A1	0.00	0.05	0.10	0.000	0.002	0.004	
A2	0.70 REF			0.028 REF			
b	0.30	0.35	0.40	0.012	0.014	0.016	
c	0.10	0.18	0.25	0.004	0.007	0.010	
D	1.80	2.10	2.20	0.071	0.083	0.087	
Е	1.15	1.24	1.35	0.045	0.049	0.053	
е	1.20	1.30	1.40	0.047	0.051	0.055	
e1	0.65 BSC				0.026 BSC	;	
L	0.20	0.38	0.56	0.008	0.015	0.022	
HE	2.00	2.10	2.40	0.079	0.083	0.095	



SOLDERING FOOTPRINT*



*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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